

Ultra Low Capacitance ESD Protection Array

FEATURES

- Meet IEC61000-4-2 (ESD) ±15kV (air), ±8kV (contact)
- Meet IEC61000-4-4 (EFT) rating. 40A (5/50ns)
- Meet IEC61000-4-5 (Lightning) rating. 5A (8/20µs)
- Protects two directional I/O lines
- Working voltage: 5V
- Pb free version and RoHS compliant
- Packing code with suffix "G" means green compound (halogen-free)

MECHANICAL DATA

- Case: MSOP-10 small outline plastic package
- Terminal: Matte tin plated, lead free., solderable per MIL-STD-202, Method 208 guaranteed
- High temperature soldering guaranteed : 260°C/10s
- Weight: 12 ± 0.5 mg
- Marking code: R0544



MSOP-10







MAXIMUM RATINGS AND ELECTRICAL CHARACTERISTICS (T _A =25°C unless otherwise noted)				
PARAMETER	SYMBOL	VALUE	UNIT	
Peak Pulse Power (tp=8/20µs waveform)	P _{PP}	125	W	
Peak Pulse Current (tp=8/20µs)	I _{PP}	5	А	
ESD per IEC 61000-4-2 (Air)	V	± 15	КV	
ESD per IEC 61000-4-2 (Contact)	V _{ESD}	± 8	rν	
Junction and Storage Temperature Range	T _J , T _{STG}	-55 to +150	°C	

PARAMETER		SYMBOL	MIN	MAX	UNIT
Reverse Stand-Off Voltage		V _{RWM}	-	5	V
Reverse Breakdown Voltage	I _R =1 mA	V _(BR)	6	-	V
Reverse Leakage Current	V _R = 5 V	I _R	-	1	μA
Clamping Voltage	I _{PP} = 1 A	N/	-	15	- v
	I _{PP} = 5 A	V _c	-	20	
Junction Capacitance	V _R =0 V , f = 1.0 MHz	CJ		1	pF



RATINGS AND CHARACTERISTICS CURVES

(T_A=25°C unless otherwise noted)











Fig. 4 Typical Junction Capacitance





ORDER INFORMATION (EXAMPLE)

TESDO5V0A ROG



Green compound code Packing code Part no.

PACKAGE OUTLINE DIMENSIONS MSOP-10



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DIM.	Unit (mm)		Unit (inch)	
DIIVI.	Min	Max	Min	Max
А	2.90	3.10	0.114	0.122
В	2.90	3.10	0.114	0.122
С	0.17	0.27	0.007	0.011
D	0.50	REF	0.020	REF
E	4.90 REF		0.193 REF	
F	-	1.11	-	0.044

SUGGEST PAD LAYOUT



DIM.	Unit (mm)	Unit (inch)
	Тур.	Тур.
А	4.10	0.161
В	0.30	0.012
С	0.50	0.020
D	1.60	0.063
Е	2.50	0.098
F	5.70	0.224

Note: 1. The suggested land pattern dimensions have been provided for reference only, as actual pad layouts may vary depending on application.



APPLICATIONS INFORMATION

- \Diamond Designed for protection of high-speed interfaces such as HDMI
- ♦ Ultra low capacitance between the pairs while being rated to handle >±8kV, ESD contact discharges and >±15kV air discharge
- \diamondsuit Each device is in a leadless package that is less than 1.1mm wide
- Obesigned such that the traces flow straight through the device. The narrow package and flow-through design reduces discontinuities and minimizes impact on signal integrity
- \diamond TESDO5V0A is ultra low capacitance ESD protection array designed to protect high speed data interfaces
- The combination of small size, low capacitance, and high level of ESD protection makes them a flexible solution for applications of high speed interface, ex HDMI, DisplayPortTM, MDDI, and eSATA interfaces

CIRCUIT BOARD LAYOUT RECOMMENDATIONS FOR HDMI APPLICATION

- ♦ The PCB traces are used to connect the pin pairs for each line (pin 1 to pin 10, pin 2 to pin 9, pin 4 to pin 7, pin 5 to pin6)
- ♦ Signal line enters at pin 1 and exits at pin 10 and PCB trace connects pin 1 and 10 together. Ground is connected at pins 3 and 8.





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